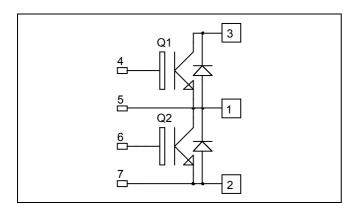


Phase leg Trench + Field Stop IGBT3 Power Module





Application

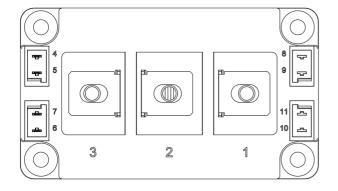
- Welding converters
- Switched Mode Power Supplies
- Uninterruptible Power Supplies
- Motor control

Features

- Trench + Field Stop IGBT3 Technology
 - Low voltage drop
 - Low tail current
 - Switching frequency up to 20 kHz
 - Soft recovery parallel diodes
 - Low diode VF
 - Low leakage current
 - RBSOA and SCSOA rated
- Kelvin emitter for easy drive
- High level of integration
- M6 power connectors



- Stable temperature behavior
- Very rugged
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Easy paralleling due to positive T_C of V_{CEsat}
- RoHS Compliant



Absolute maximum ratings

Symbol	Parameter		Max ratings	Unit
V_{CES}	Collector - Emitter Breakdown Voltage		1200	V
Ţ	Continuous Collector Current	$T_C = 25$ °C	580	
$I_{\rm C}$	Continuous Conector Current	$T_C = 80$ °C	400	Α
I_{CM}	Pulsed Collector Current	$T_C = 25$ °C	800	
V_{GE}	Gate – Emitter Voltage		±20	V
P_{D}	Maximum Power Dissipation	$T_C = 25^{\circ}C$	2100	W
RBSOA	Reverse Bias Safe Operating Area	$T_{j} = 125^{\circ}C$	800A @ 1100V	

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com



All ratings @ $T_j = 25$ °C unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
I_{CES}	Zero Gate Voltage Collector Current	$V_{GE} = 0V, V_{CE} = 1200V$				750	μA
V _{CE(sat)}	Collector Emitter saturation Voltage	$V_{GE} = 15V$	$T_j = 25$ °C		1.7	2.1	V
	Conector Emitter saturation voltage	$I_{\rm C} = 400 A$	$T_j = 125$ °C		2.0		v
$V_{GE(th)}$	Gate Threshold Voltage	$V_{GE} = V_{CE}$, $I_C = 12mA$		5.0	5.8	6.5	V
I_{GES}	Gate – Emitter Leakage Current	$V_{GE} = 20V, V_{CE} = 0V$				400	nA

Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min	Тур	Max	Unit
C_{ies}	Input Capacitance	$V_{GE} = 0V ; V_{CE} = 25V$		29		nF
C_{res}	Reverse Transfer Capacitance	f = 1MHz		1.3		ПГ
Q_{G}	Gate charge	V_{GE} =±15V, I_{C} =400A V_{CE} =600V		3.7		μС
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching (25°C)		250		ns
$T_{\rm r}$	Rise Time	$V_{GE} = \pm 15V$		90		
$T_{d(off)}$	Turn-off Delay Time	$V_{\text{Bus}} = 600V$ $I_{\text{C}} = 400A$		550		
T_{f}	Fall Time	$R_G = 1.8\Omega$		130		
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching (125°C	2)	300		ns
T_{r}	Rise Time	$V_{GE} = \pm 15V$		100		
$T_{d(off)}$	Turn-off Delay Time	$V_{\text{Bus}} = 600V$ $I_{\text{C}} = 400A$		650		
$T_{\rm f}$	Fall Time	$R_G = 1.8\Omega$		180		
Eon	Turn on Energy	$V_{GE} = \pm 15V$ $V_{Bus} = 600V$ $T_j = 125^{\circ}0$	C	36		mJ
E_{off}	Turn off Energy	$I_C = 400A$ $R_G = 1.8\Omega$ $T_j = 125^{\circ}$	C	62		1113
I_{sc}	Short Circuit data	$V_{GE} \le 15V$; $V_{Bus} = 900V$ $t_p \le 10 \mu s$; $T_i = 125 ^{\circ}C$		1600		A

Reverse diode ratings and characteristics

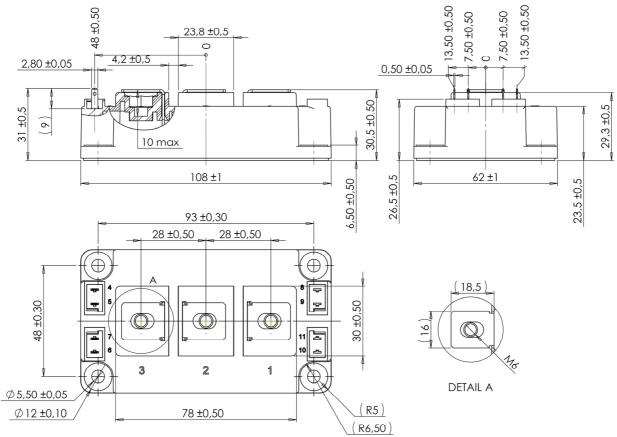
Symbol	Characteristic	Test Conditions		Min	Тур	Max	Unit
V_{RRM}	Maximum Peak Repetitive Reverse Voltage			1200			V
I_{RRM}	Maximum Reverse Leakage Current	V _R =1200V	$T_i = 25$ °C $T_i = 125$ °C			750 1000	μΑ
I_F	DC Forward Current		$Tc = 80^{\circ}C$		400		A
\mathbf{V}_{r}	V_F Diode Forward Voltage $ I_F = 400A \\ V_{GE} = 0V $		$T_i = 25^{\circ}C$		1.6	2.1	V
V F		$T_j = 125$ °C		1.6		V	
+	Reverse Recovery Time		$T_j = 25^{\circ}C$		170		ns
t _{rr}	Reverse Recovery Time		$T_j = 125$ °C		280		115
	Reverse Recovery Charge	$I_F = 400A$ $V_R = 600V$ $di/dt = 4000A/\mu s$	$T_j = 25^{\circ}C$		36		C
Q_{rr}			$T_{i} = 125^{\circ}C$		72		μC
E _{rr}	D	αι/αι 4000Α/μ3	$T_j = 25$ °C		20		m I
	Reverse Recovery Energy		$T_{j} = 125^{\circ}C$		36		mJ



Thermal and package characteristics

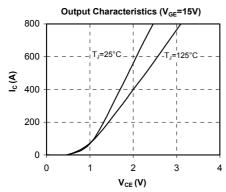
Symbol	Characteristic			Min	Тур	Max	Unit
R_{thJC}	Junction to Case Thermal Resistance		IGBT			0.06	°C/W
IX _{th} JC			Diode			0.13	
V_{ISOL}	RMS Isolation Voltage, any terminal to case t = 1 min, 50/60Hz			4000			V
T_{J}	Operating junction temperature range		-40		150		
T_{STG}	Storage Temperature Range			-40		125	°C
$T_{\rm C}$	Operating Case Temperature			-40		125	
Torque	Mounting torque	For terminals	M6	3		5	N.m
Torque		To Heatsink	M6	3		5	18.111
Wt	Package Weight					350	g

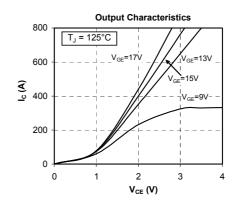
D3 Package outline (dimensions in mm)

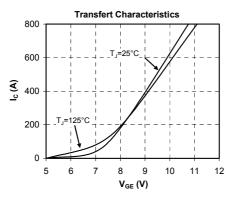


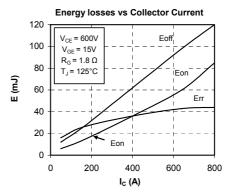


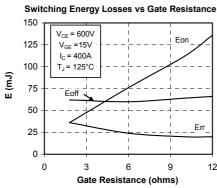
Typical Performance Curve

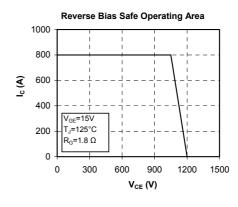


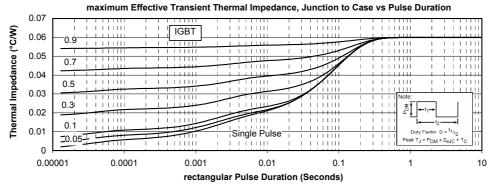








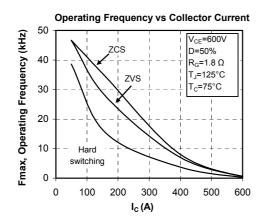


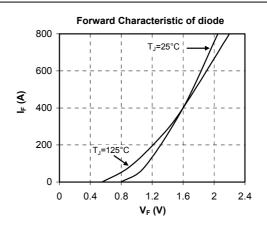


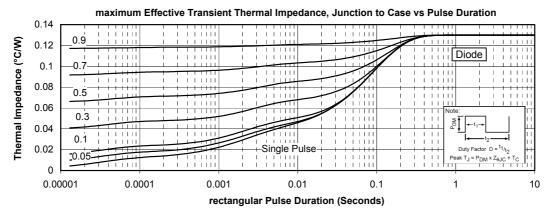
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